Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.024”**

**.024”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: E = .0035” X .0035” B = .003” X .0035”**

**Backside Potential: Collector**

**Mask Ref: VHB**

**APPROVED BY: DK DIE SIZE .024” X .024” DATE: 9/7/21**

**MFG: ALLEGRO THICKNESS .007” P/N: 2N2605**

**DG 10.1.2**

#### Rev B, 7/19/02